2SA1748

Silicon PNP epitaxial planar type

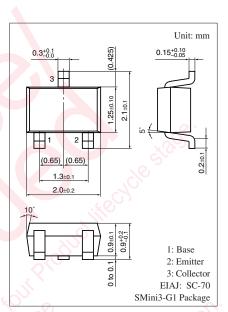
For high-frequency amplification Complementary to 2SC4562

Features

- High transition frequency f_T
- \bullet Small collector output capacitance C_{ob}
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

Absolute Maximum Ratings $T_a = 25$ C					
Parameter	Symbol	Rating	Unit		
Collector-base voltage (Emitter open)	V _{CBO}	-50	v		
Collector-emitter voltage (Base open)	V _{CEO}	-50	V		
Emitter-base voltage (Collector open)	V _{EBO}	-5	V		
Collector current	I _C	-50	mA		
Collector power dissipation	P _C	150	mW		
Junction temperature	Tj	150	°C		
Storage temperature	T _{stg}	-55 to +150	۰°C		





Marking Symbol: AL

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

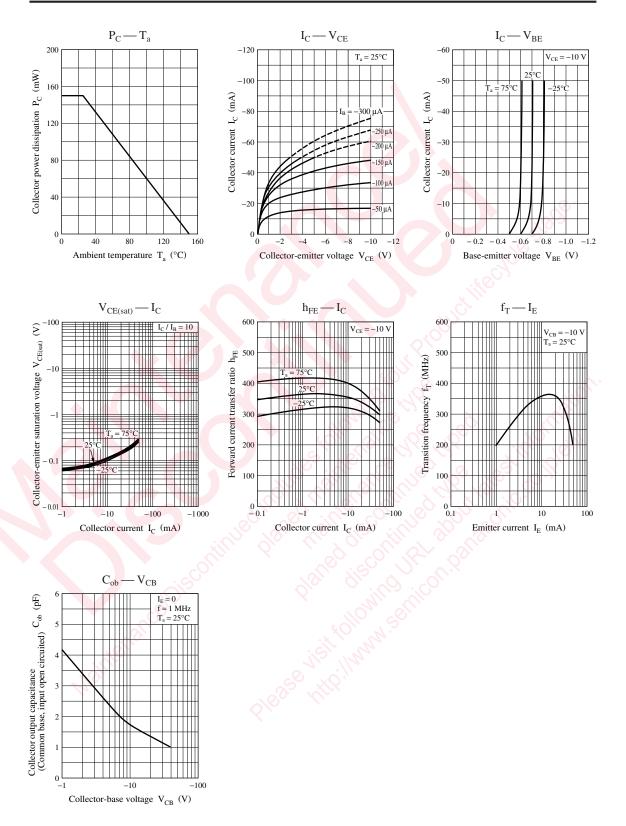
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu A, \ I_{\rm E} = 0$	-50	22		V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -1 \text{ mA}, I_{\rm B} = 0$	-50			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = -10 \ \mu A, I_{\rm C} = 0$	-5			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = -10 \text{ V}, I_E = 0$			- 0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -10 \text{ V}, I_B = 0$			-100	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CE} = -10 \text{ V}, I_C = -2 \text{ mA}$	200		500	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -1 \text{ mA}$		- 0.1	- 0.3	V
Transition frequency	f _T	$V_{CB} = -10$ V, $I_E = 2$ mA, $f = 200$ MHz		250		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		1.5		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Q	R
h _{FE}	200 to 400	250 to 500

Panasonic



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